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## RESPONSE UNDER 37 CFR 1.116 EXPEDITED PROCEDURE

## IN THE U.S. PATENT AND TRADEMARK OFFICE

January 16, 2009

Applicants: Atsushi YABE et al

For: ELECTROLESS COPPER PLATING SOLUTION AND

ELECTROLESS COPPER PLATING METHOD

Serial No.: 10/576 230 Group: 1792

Confirmation No.: 7180

Filed: April 14, 2006 Examiner: Bareford

International Application No.: PCT/JP2004/014049

International Filing Date: September 17, 2004

Atty. Docket No.: 4700.P0328US

Mail Stop AF Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

## AMENDMENT AFTER FINAL REJECTION

Sir:

In response to the Office Action dated October 20, 2008, please amend the above-identified application as follows:

(Please see following pages.)

## CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on <u>January 16, 2009</u>.

Terrygace F. Chapman